

840-AG11D-ESL-LF

x OBSOLETE

DIPLOMATE

TE Internal #: 3-1571552-2

TE Internal Description: 840-AG11D-ESL-LF=800 DIP,GF/SN

DIP Socket: Standard, Stamped & Formed, Open, Gold

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Connectors > Socket Connectors > IC Sockets > DIP Sockets > DIP Socket: Standard, Stamped & Formed, Open, Gold



Contact Fabrication: **Stamped & Formed**

Number of Positions: **40**

Connector Profile: **Standard**

Row-to-Row Spacing: **15.24 mm [.6 in]**

Contact Mating Area Plating Material: **Gold**

Features

Product Type Features

| | |
|-----------------------------------|-----------------------|
| Connector & Contact Terminates To | Printed Circuit Board |
|-----------------------------------|-----------------------|

Configuration Features

| | |
|-----------------------|----------|
| Number of Rows | 2 |
| PCB Mount Orientation | Vertical |
| Number of Positions | 40 |

Electrical Characteristics

| | |
|-----------------------|---------|
| Insulation Resistance | 5000 MΩ |
| Contact Resistance | 10 mΩ |

Body Features

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|-------------------------|--------------|
| Sleeve Material | Brass |
| Sleeve Plating Material | Tin |
| Frame Style | Ladder, Open |
| Connector Profile | Standard |

Contact Features

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|--|--|
| | |
|--|--|



| | |
|---|------------------|
| Mating Contact Type | Four-Fingered |
| IC Socket Type | DIP |
| Contact Type | Pin |
| PCB Contact Termination Area Plating Material | Tin |
| Contact Base Material | Beryllium Copper |
| Contact Fabrication | Stamped & Formed |
| Contact Mating Area Plating Material | Gold |
| | 5 µin |
| Contact Current Rating (Max) | 3 A |

Termination Features

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|---|-----------------------|
| Termination Post & Tail Length | 3.18 mm[.125 in] |
| Termination Method to Printed Circuit Board | Through Hole - Solder |

Mechanical Attachment

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|-------------------------|--------------|
| Mating Alignment Type | Polarization |
| Mating Alignment | With |
| Connector Mounting Type | Board Mount |

Housing Features

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|--------------------|-------------------------|
| Housing Material | Thermoplastic Polyester |
| Housing Color | Black |
| Centerline (Pitch) | 2.54 mm[.1 in] |

Dimensions

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|-------------------------|------------------|
| Profile Height from PCB | 2.67 mm[.105 in] |
| Product Length | 50.8 mm[2 in] |
| Row-to-Row Spacing | 15.24 mm[.6 in] |

Usage Conditions

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|-----------------------------|----------------------------|
| Operating Temperature Range | -55 - 105 °C[-67 - 221 °F] |
|-----------------------------|----------------------------|

Operation/Application

| | |
|---------------------|--------|
| Circuit Application | Signal |
|---------------------|--------|

Industry Standards

| | |
|------------------------|----------|
| UL Flammability Rating | UL 94V-0 |
|------------------------|----------|

Packaging Features

| | |
|---------------|-----|
| Tubes per Box | 100 |
|---------------|-----|



| | |
|--------------------|------------------|
| Packaging Quantity | 12 |
| Packaging Method | Box & Tube, Tube |

Other

| | |
|-------------------|----|
| Quantity per Tube | 12 |
|-------------------|----|

Product Compliance


For compliance documentation, visit the product page on [TE.com](#)>

| | |
|---|---|
| EU RoHS Directive 2011/65/EU | Compliant |
| EU ELV Directive 2000/53/EC | Compliant |
| China RoHS 2 Directive MIIT Order No 32, 2016 | No Restricted Materials Above Threshold |
| EU REACH Regulation (EC) No. 1907/2006 | Current ECHA Candidate List: JAN 2024 (240) Candidate List Declared Against: JAN 2021 (211) Does not contain REACH SVHC |
| Halogen Content | Not Low Halogen - contains Br or Cl > 900 ppm. |
| Solder Process Capability | Wave solder capable to 265°C |

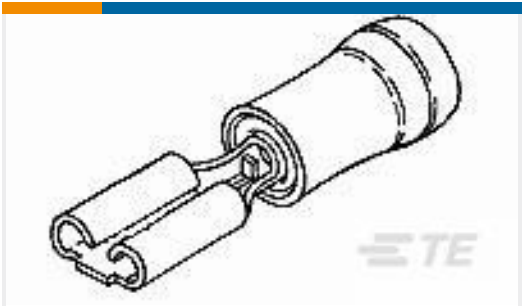
Product Compliance Disclaimer

This information is provided based on reasonable inquiry of our suppliers and represents our current actual knowledge based on the information they provided. This information is subject to change. The part numbers that TE has identified as EU RoHS compliant have a maximum concentration of 0.1% by weight in homogenous materials for lead, hexavalent chromium, mercury, PBB, PBDE, DBP, BBP, DEHP, DIBP, and 0.01% for cadmium, or qualify for an exemption to these limits as defined in the Annexes of Directive 2011/65/EU (RoHS2). Finished electrical and electronic equipment products will be CE marked as required by Directive 2011/65/EU. Components may not be CE marked. Additionally, the part numbers that TE has identified as EU ELV compliant have a maximum concentration of 0.1% by weight in homogenous materials for lead, hexavalent chromium, and mercury, and 0.01% for cadmium, or qualify for an exemption to these limits as defined in the Annexes of Directive 2000/53/EC (ELV). Regarding the REACH Regulation, the information TE provides on SVHC in articles for this part number is based on the latest European Chemicals Agency (ECHA) 'Guidance on requirements for substances in articles' posted at this URL: <https://echa.europa.eu/guidance-documents/guidance-on-reach>

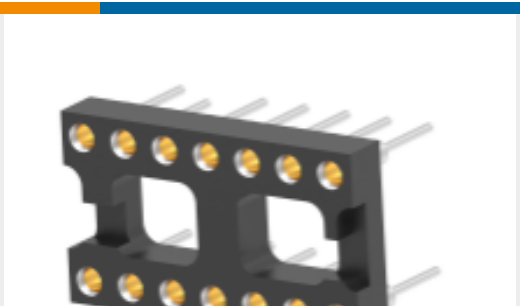
Customers Also Bought




TE Part # 342103-1
22-16 F.E.P.G. RING TONGUE NO.



TE Part # 165616-2
110 PIDG FASTON REC



TE Part # 2-1571552-5
DIP Socket: Standard, Stamped & Formed, Open, Gold



TE Part # 2-1571552-4
816-AG11D-ESL-LF=800 DIP,GF/SN



Documents

Product Drawings

840-AG11D-ESL-LF=800 DIP,GF/SN

English

CAD Files

3D PDF

3D

Customer View Model

ENG_CVM_CVM_3-1571552-2_E.2d_dxf.zip

English

Customer View Model

ENG_CVM_CVM_3-1571552-2_E.3d_igs.zip

English

Customer View Model

ENG_CVM_CVM_3-1571552-2_E.3d_stp.zip

English

By downloading the CAD file I accept and agree to the [Terms and Conditions](#) of use.

Datasheets & Catalog Pages

DIP Sockets Quick Reference Guide (EN)

English